

ABSTRACT OF THE DISCLOSURE

An optical sensor package capable of being surface mounted, and in a form that enables multiple packages to be fabricated simultaneously and then array tested in a wafer stack prior to singulation. The package comprises a chip carrier, a device chip electrically and mechanically connected to a first surface of the chip carrier with solder connections, and a capping chip secured to the chip carrier to hermetically enclose the device chip. The device chip has an optical sensing element on a surface thereof, while the capping chip has means for enabling radiation to pass therethrough to the device chip. The chip carrier includes conductive vias that are electrically connected to the solder connections of the device chip and extend through the chip carrier to bond pads on a second surface of the chip carrier, enabling the package to be surface mounted with solder connections to a suitable substrate.